

Reutlingen wafer fab

October 7, 2019

PI 11031 BBM Fi/af

- ▶ Production facilities
 - 150-millimeter technology since 1995
 - 200-millimeter technology since 2010
 - Test center for semiconductors
 - Semiconductors have been manufactured at the wafer fab in Reutlingen since 1971.
- ▶ Clean room surface area
 - 23,400 m²
- ▶ Associates
 - 3,500
- ▶ Manufacturing technology
 - Partly automated semiconductor production (150-and 200-mm silicon substrates (wafers) with structural widths of up to 180 nm; 1 nm is a millionth of a millimeter)
- ▶ Manufactured products
 - Application-specific integrated circuits (ASICs), microelectromechanical systems(MEMS), power semiconductors
- ▶ Fields of application for semiconductors
 - Automotive electronics: ESP electronic stability program, electronic control units for IC engines and electric motors as well as for transmissions, airbag and driver assistance systems, parking assistants, and night vision enhancement systems
 - Consumer electronics: smartphones, laptops, wearables, hearables, games consoles, drones